



Material Content Data Sheet



Sales Product Name		IPG20N10S4L-35		Issued		4. July 2019		
MA#		MA005344101						
Package		PG-TDSON-8-4		Weight*		96.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.057	1.09	1.09	10929	10929
chip_2	inorganic material	silicon	7440-21-3	1.057	1.09	1.09	10929	10929
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.044	0.05		460	
wire	non noble metal	copper	7440-50-8	44.409	45.94	46.00	459279	459877
	non noble metal	aluminium	7429-90-5	0.837	0.87	0.87	8658	8658
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		933	
	plastics	epoxy resin	-	6.404	6.62		66234	
leadfinish	inorganic material	silicondioxide	60676-86-0	38.607	39.93	46.64	399273	466440
	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13524	13524
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	496	497
solder	non noble metal	tin	7440-31-5	0.051	0.05		532	
	noble metal	silver	7440-22-4	0.064	0.07		665	
heatspreader	non noble metal	lead	7439-92-1	2.457	2.54	2.66	25412	26609
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
*deviation	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2533	2537
					Sum in total:		100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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